100% Material Declaration Data Sheet FG256

Average Weight: 0.9408 g

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
Silicon Die					**0.0749**	**7.97%**
	Silicon	7440-21-3	100.00		0.0749	
Die Attach Material					**0.0074**	**0.78%**
	Silver	7440-22-4	78.00		0.0058	
	Resin	Trade Secret	22.00		0.0016	
Mold Compound					**0.3748**	**39.84%**
	Epoxy Resins	Trade Secret	12.00		0.0450	
	SiO2	60676-86-0	88.00	Filler	0.3298	
Laminate					**0.2085**	**22.16%**
	Laminate	Trade Secret	61.00		0.1272	
	Solder Mask	Trade Secret	17.36		0.0362	
	Copper	7440-50-8	16.00	Metal Layer	0.0334	
	Nickel	7440-02-0	4.80	Metal Layer	0.0100	
	Gold	7440-57-5	0.84	Metal Layer	0.0018	
Bond Wire					**0.0043**	**0.46%**
	Gold	7440-57-5	99.00		0.004263581	
	Silver	7440-22-4	0.0025		0.000000108	
	Copper	7440-50-8	0.0005		0.000000022	
	Iron	7439-89-6	0.0005		0.000000022	
	Calcium	7440-70-2	0.0020		0.000000086	
	Palladium	7440-05-3	0.9900		0.000042636	
	Magnesium	7439-95-4	0.0005		0.000000022	
Solder Balls					**0.2709**	**28.79%**
	Tin	7440-31-5	63.00		0.170667	
	Lead	7439-92-1	37.00		0.100233	

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Xilinx believes this environmental information to be correct, but cannot guarantee its completeness or accuracy as it is based on data received from sources outside our company.
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Revision History

The following table shows the revision history for this document.

Date	Revision	Revision
3/21/06	1.0	Initial release.
7/11/06	1.1	100% Material Declaration.
9/14/06	1.2	Deleted component description.

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